

Title (en)

MECHANICAL PACKAGING TECHNIQUE OF ATTACHING MEMS AND FLEX CIRCUIT

Title (de)

MECHANISCHE VERPACKUNGSTECHNIK ZUR BEFESTIGUNG VON MEMS- UND FLEXIBLEN SCHALTUNGEN

Title (fr)

TECHNIQUE D'ENCAPSULATION MÉCANIQUE POUR LA CONNEXION DE MICROSYSTÈME ÉLECTROMÉCANIQUE ET DE CIRCUIT SOUPLE

Publication

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Application

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Abstract (en)

[origin: WO2013078006A1] The present invention disclosed provides for a rugged, compact sensing device for various implementations including those of automotive, marine, and other combustion technologies that require low cost accurate pressure sensing during internal combustion engine process. In one or more aspects of the present invention, a MEMS sensor connection with a flexible circuit is presented and the communication of which is preferably achieved through the use of wire bond technology.

IPC 8 full level

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Citation (third parties)

Third party : Jan Reininger

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